

**$V_{BR(CES)} = 400\text{ V}$ ,  $I_C = 20\text{ A}$**   
**N-channel Ignition IGBT**  
**DGU4020GR**

**Description**

The DGU4020GR is 400 V IGBT with Zener diodes and gate resistors, and achieves an ignition coil drive circuit without an external clamped circuit. The IGBT has low saturation characteristic, and can improve the efficiency of the circuit.

**Features**

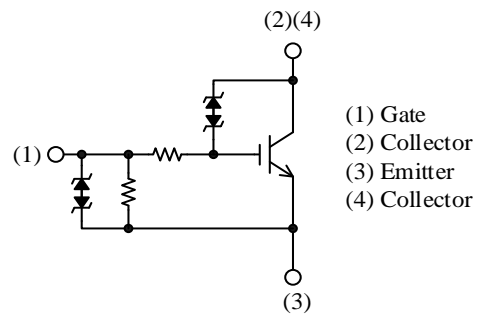
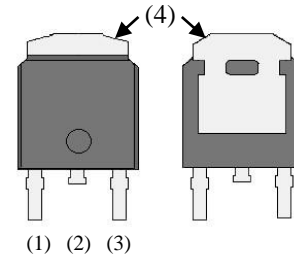
- AEC-Q101 Qualified
  - Bare Lead Frame: Pb-free (RoHS Compliant)
  - Built-in Zener Diodes
  - Built-in Gate Resistors
  - Low Saturation Voltage
- 
- $V_{(BR)CES}$  ----- 400 V
  - $I_C$  ----- 20 A
  - $V_{CE(SAT)}$  ----- 1.10 V typ. ( $V_{GE} = 4.5\text{ V}$ ,  $I_C = 10\text{ A}$ )

**Applications**

- Ignition Coil Driver Circuits

**Packages**

TO252-2L



Not to scale

**Absolute Maximum Ratings**

Unless otherwise specified,  $T_A = 25\text{ }^\circ\text{C}$ .

Parameter	Symbol	Conditions	Rating	Unit
Collector-to-Emitter Voltage	$V_{CE}$		$V_{(BR)CES}$	V
Gate-to-Emitter Voltage	$V_{GE}$		$\pm 10$	V
Continuous Collector Current	$I_C$	$T_C = 25\text{ }^\circ\text{C}$	20	A
Power Dissipation	$P_D$	$T_C = 25\text{ }^\circ\text{C}$	172	W
Self-clamped Inductive Switching Energy	$E_{SCIS}$	See Figure 1 and Equation (1).	320	mJ
Self-clamped Inductive Switching Current	$I_{SCIS}$	$V_{CC} = 14\text{ V}$ , $V_{GE} = 5\text{ V}$ , $L = 1.6\text{ mH}$ , $R_G = 1\text{ k}\Omega$	20	A
Reverse Avalanche Energy	$E_{AS(R)}$	$L = 6\text{ mH}$	2000	mJ
Operating Junction Temperature	$T_J$		-40 to 175	$^\circ\text{C}$
Storage Temperature	$T_{STG}$		-40 to 175	$^\circ\text{C}$

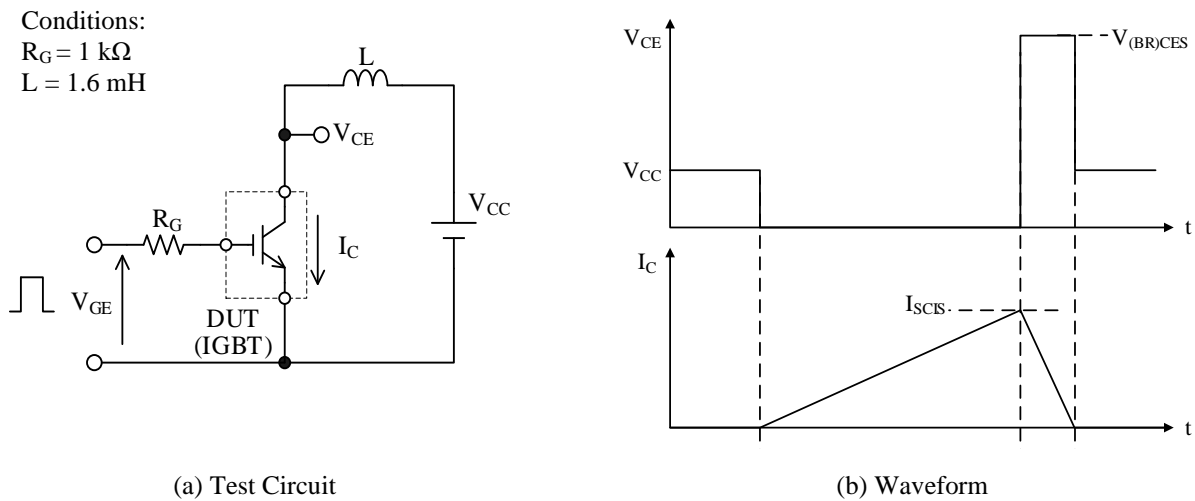


Figure 1. Self-clamped Inductive Switching Energy Test

$$E_{SCIS} = \frac{1}{2} \times L \times I_{SCIS}^2 \times \frac{V_{(BR)CES}}{V_{(BR)CES} - V_{CC}} \tag{1}$$

**Electrical Characteristics**

Unless otherwise specified,  $T_A = 25\text{ }^\circ\text{C}$ .

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Collector-to-Emitter Breakdown Voltage	$V_{(BR)CES}$	$I_C = 2\text{ mA}$ , $V_{GE} = 0\text{ V}$	375	400	425	V	
Gate-to-Emitter Breakdown Voltage	$V_{(BR)GES}$	$I_G = \pm 1\text{ mA}$ , $V_{CE} = 0\text{ V}$	$\pm 10.0$	$\pm 11.5$	$\pm 13.0$	V	
Collector-to-Emitter Leakage Current	$I_{CES}$	$V_{CE} = 300\text{ V}$ , $V_{GE} = 0\text{ V}$	—	—	100	$\mu\text{A}$	
Emitter-to-Collector Leakage Current	$I_{ECS}$	$V_{EC} = 24\text{ V}$	—	—	1.0	mA	
Gate-to-Emitter Leakage Current	$I_{GES}$	$V_{GE} = \pm 5\text{ V}$	$\pm 89$	$\pm 106$	$\pm 132$	$\mu\text{A}$	
Gate Threshold Voltage	$V_{GE(TH)}$	$V_{CE} = 10\text{ V}$ , $I_C = 1\text{ mA}$	1.40	1.75	2.10	V	
Collector-to-Emitter Saturation Voltage	$V_{CE(SAT)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_{GE} = 3.5\text{ V}$ , $I_C = 10\text{ A}$	—	1.16	1.39	V
			$V_{GE} = 4.5\text{ V}$ , $I_C = 10\text{ A}$	—	1.10	1.32	V
			$V_{GE} = 4.5\text{ V}$ , $I_C = 15\text{ A}$	—	1.25	1.50	V
			$V_{GE} = 4.5\text{ V}$ , $I_C = 20\text{ A}$	—	1.39	1.67	V
		$T_J = 150\text{ }^\circ\text{C}$	$V_{GE} = 3.5\text{ V}$ , $I_C = 10\text{ A}$	—	1.15	1.50	V
			$V_{GE} = 4.5\text{ V}$ , $I_C = 10\text{ A}$	—	1.08	1.40	V
			$V_{GE} = 4.5\text{ V}$ , $I_C = 15\text{ A}$	—	1.31	1.77	V
			$V_{GE} = 4.5\text{ V}$ , $I_C = 20\text{ A}$	—	1.58	2.13	V
Input Capacitance	$C_{ies}$	$V_{CE} = 10\text{ V}$ , $V_{GE} = 0\text{ V}$ , $f = 1.0\text{ MHz}$	—	1900	—	pF	
Output Capacitance	$C_{oes}$		—	460	—	pF	
Reverse Transfer Capacitance	$C_{res}$		—	160	—	pF	
Turn-on Delay Time	$t_{d(ON)}$	Resistive load, see Figure 3	—	1.3	—	$\mu\text{s}$	
Rise Time	$t_r$		—	3.8	—	$\mu\text{s}$	
Turn-off Delay Time	$t_{d(OFF)}$	Inductive load, see Figure 4	—	13.5	—	$\mu\text{s}$	
Fall Time	$t_f$		—	2.7	—	$\mu\text{s}$	
Internal Series Gate Resistor <sup>(1)</sup>	$R_{G(INT)}$		—	70	—	$\Omega$	
Internal Gate-to-Emitter Resistor <sup>(1)</sup>	$R_{GE(INT)}$	$T_J = -40\text{ to }175\text{ }^\circ\text{C}$	37.6	47.0	$61.1^{(2)}$	k $\Omega$	

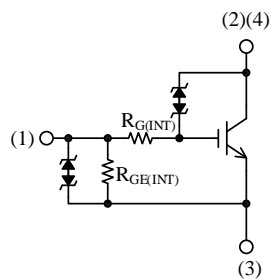


Figure 2. Internal Gate Resistor

<sup>(1)</sup> See Figure 2.

<sup>(2)</sup> Guaranteed by design.

## DGU4020GR

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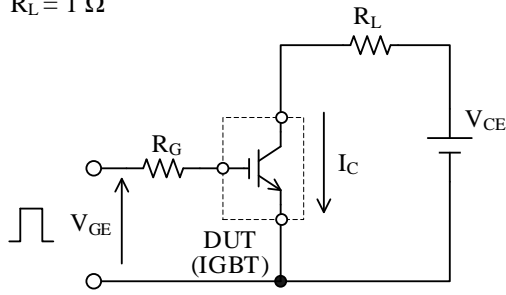
### Thermal Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Thermal Resistance (Junction-to-Case)	$R_{\theta JC}$		—	—	0.87	°C/W

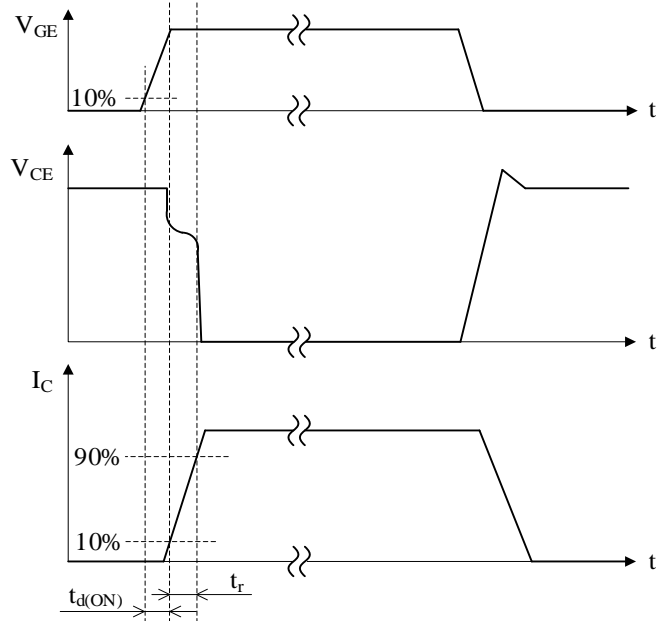
### Mechanical Characteristics

Parameter	Conditions	Min.	Typ.	Max.	Unit
Package Weight		—	0.32	—	g

Conditions:  
 $V_{CE} = 14\text{ V}$   
 $V_{GE} = 5\text{ V}$   
 $R_G = 1\text{ k}\Omega$   
 $R_L = 1\ \Omega$



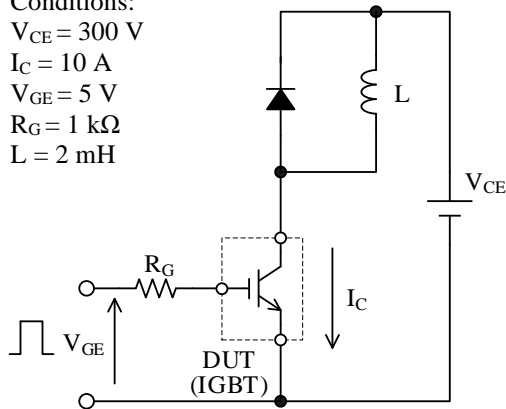
(a) Test Circuit



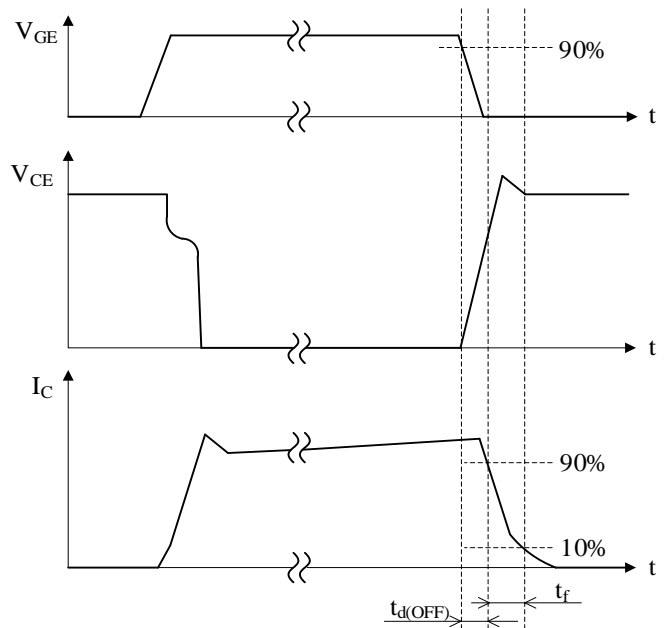
(b) Waveform

Figure 3. Switching Time Test in Resistive Load

Conditions:  
 $V_{CE} = 300\text{ V}$   
 $I_C = 10\text{ A}$   
 $V_{GE} = 5\text{ V}$   
 $R_G = 1\text{ k}\Omega$   
 $L = 2\text{ mH}$



(a) Test Circuit



(b) Waveform

Figure 4. Switching Time Test in Inductive Load

Rating and Typical Characteristic Curves

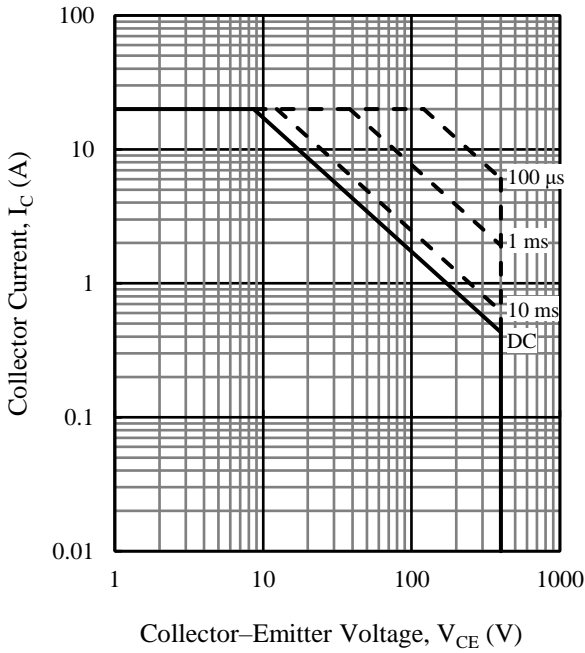


Figure 5. Safe Operating Area

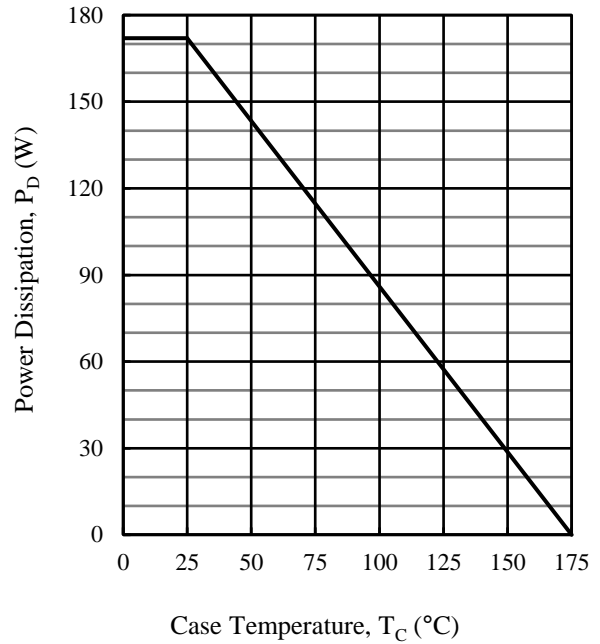


Figure 6. Typical Characteristics:  $P_D$  vs.  $T_C$

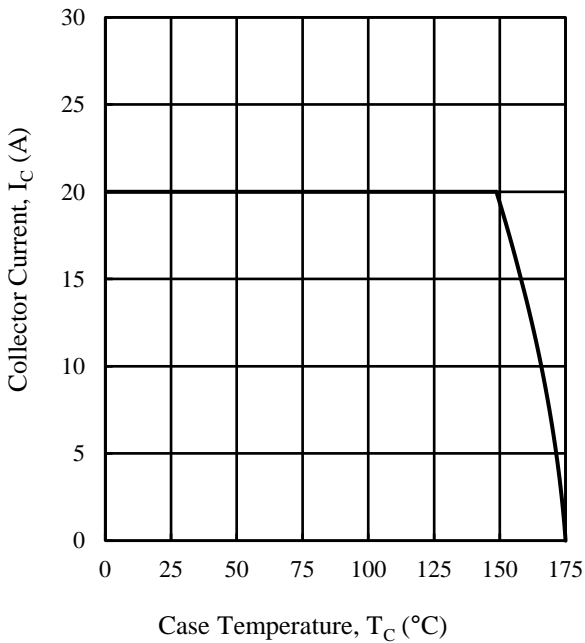


Figure 7. Typical Characteristics:  $I_C$  vs.  $T_C$   
( $V_{GE} = 5$  V)

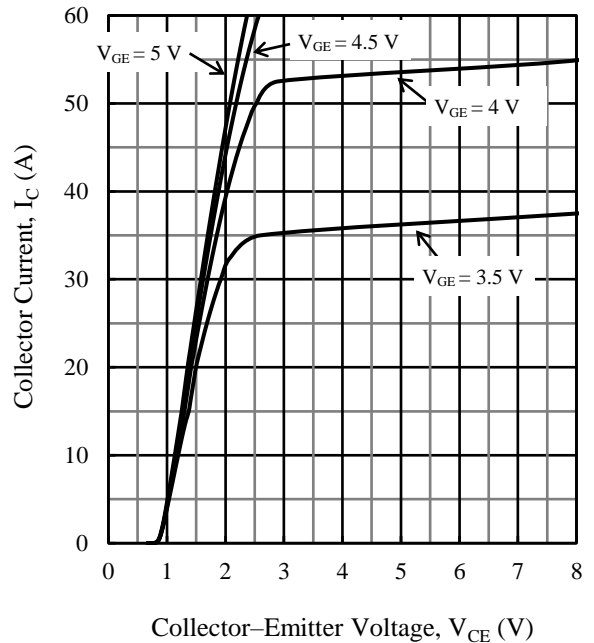


Figure 8. Typical Characteristics:  $I_C$  vs.  $V_{CE}$   
( $T_J = -40$  °C)

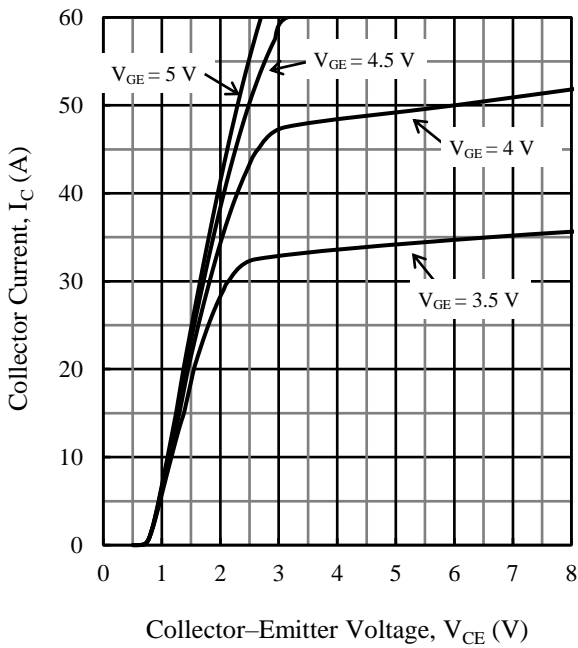


Figure 9. Typical Characteristics:  $I_C$  vs.  $V_{CE}$  ( $T_J = 25\text{ }^\circ\text{C}$ )

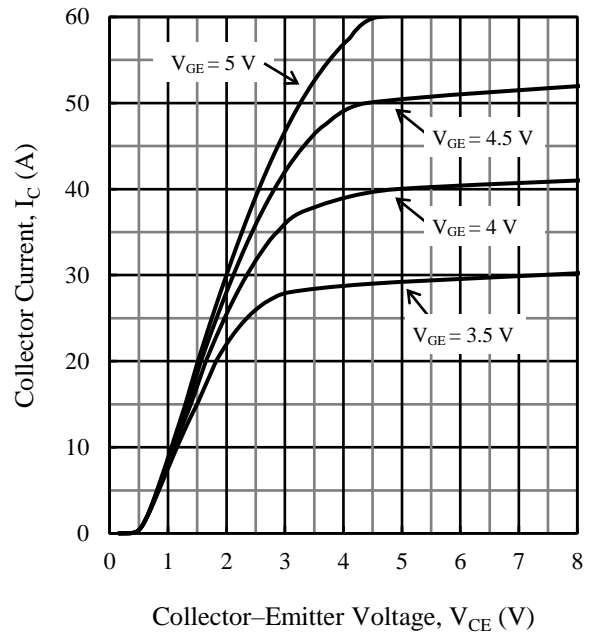


Figure 10. Typical Characteristics:  $I_C$  vs.  $V_{CE}$  ( $T_J = 175\text{ }^\circ\text{C}$ )

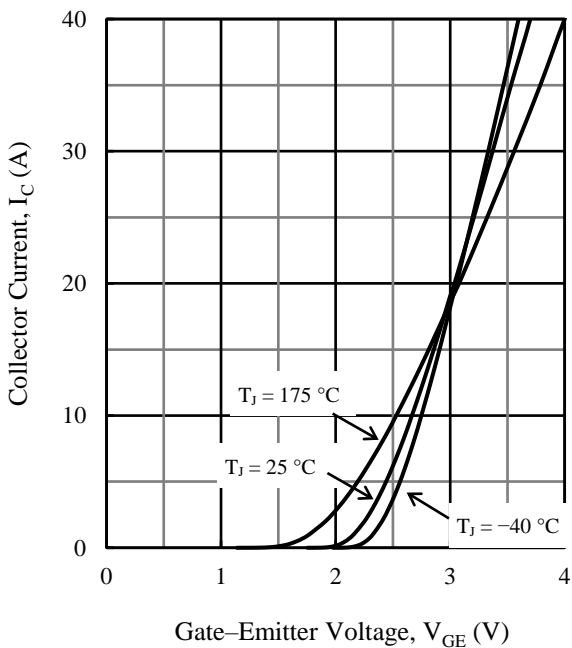


Figure 11. Typical Characteristics:  $I_C$  vs.  $V_{GE}$  ( $V_{CE} = 5\text{ V}$ )

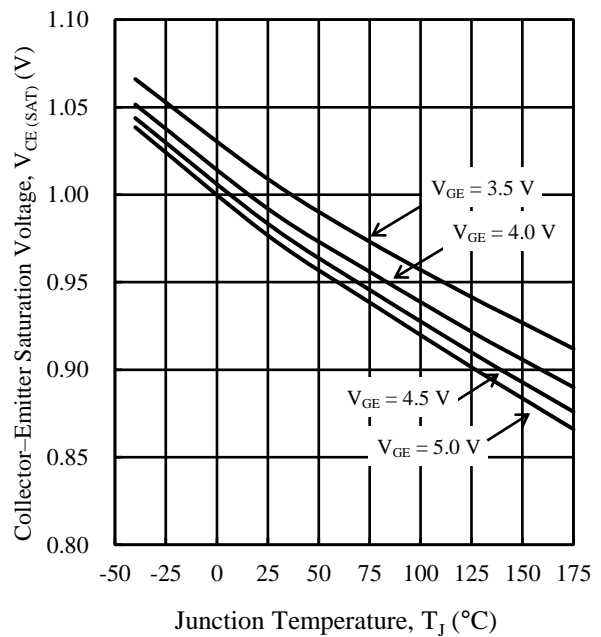


Figure 12. Typical Characteristics:  $V_{CE(SAT)}$  vs.  $T_J$  ( $I_C = 6\text{ A}$ )

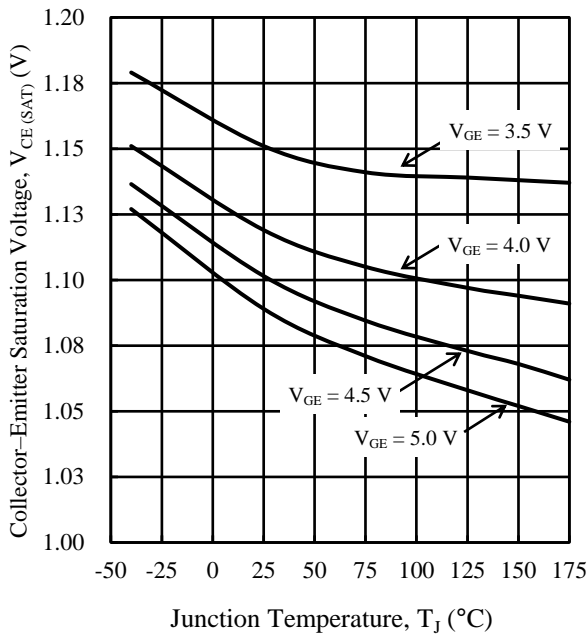


Figure 13. Typical Characteristics:  $V_{CE(SAT)}$  vs.  $T_J$  ( $I_C = 10\text{ A}$ )

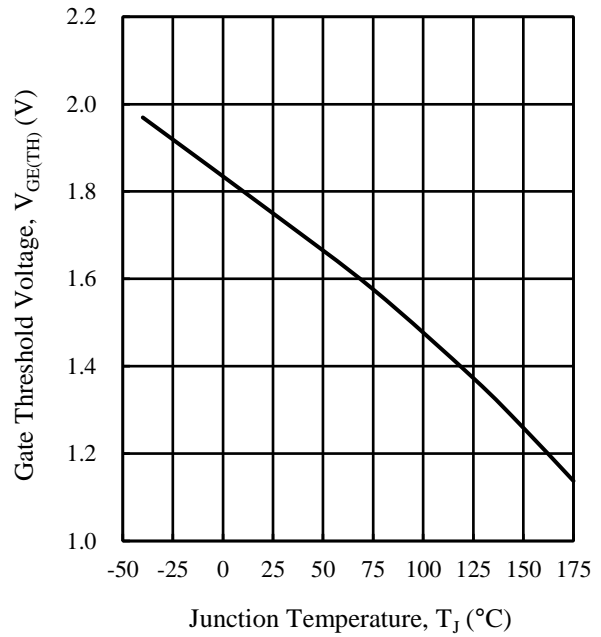


Figure 14. Typical Characteristics:  $V_{GE(TH)}$  vs.  $T_J$  ( $V_{CE} = 10\text{ V}$ ,  $I_C = 1\text{ mA}$ )

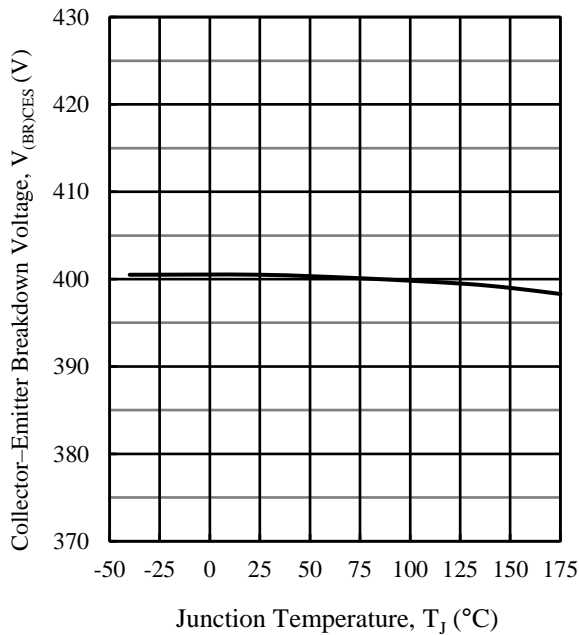


Figure 15. Typical Characteristics:  $V_{(BR)CES}$  vs.  $T_J$  ( $V_{CE} = 0\text{ V}$ ,  $I_C = 2\text{ mA}$ )

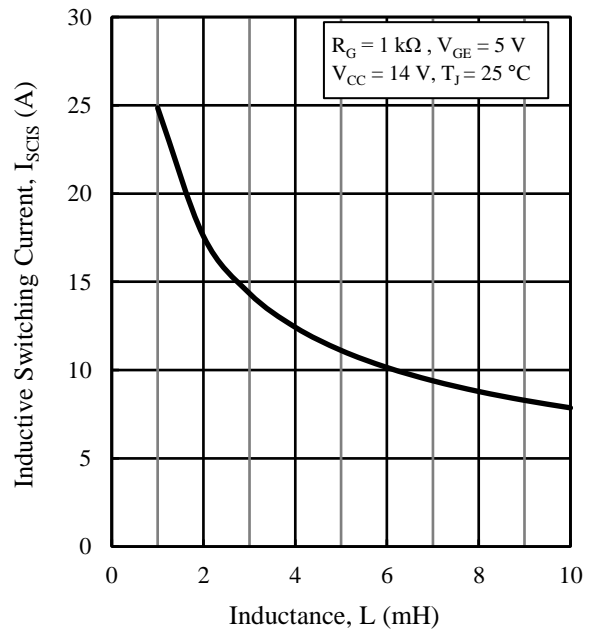


Figure 16. Typical Characteristics:  $I_{SCIS}$  vs.  $L$



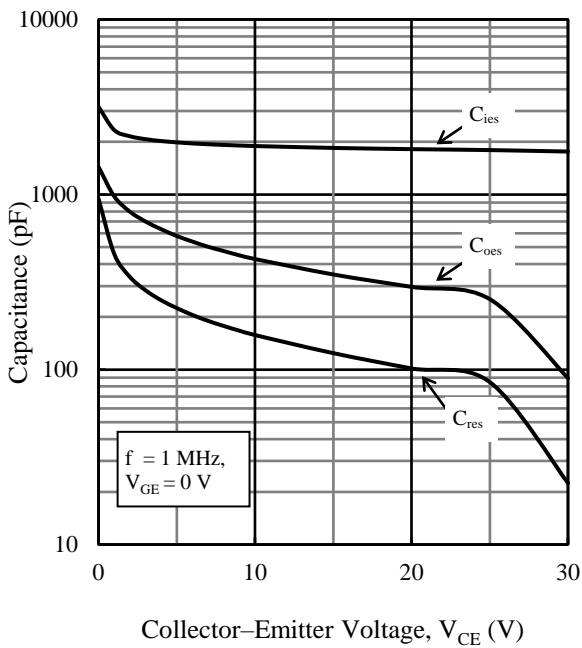


Figure 17. Typical Characteristics:  
Capacitance vs.  $V_{CE}$

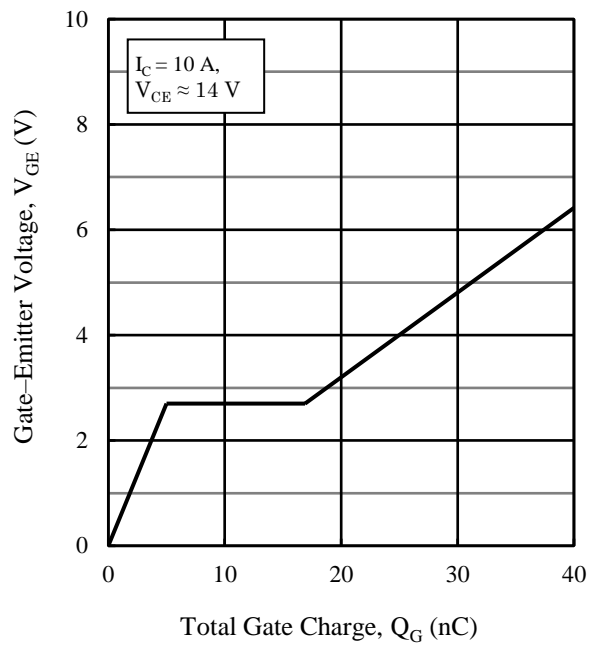


Figure 18. Typical Characteristics:  $V_{GE}$  vs.  $Q_G$

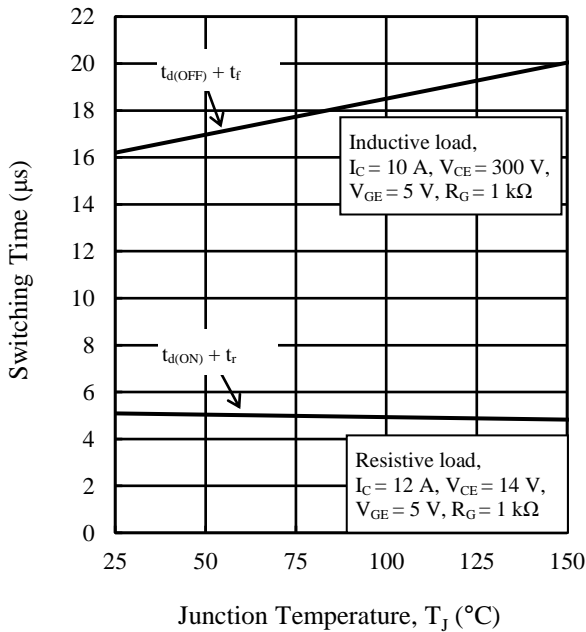


Figure 19. Typical Characteristics:  
Switching Time vs.  $T_J$

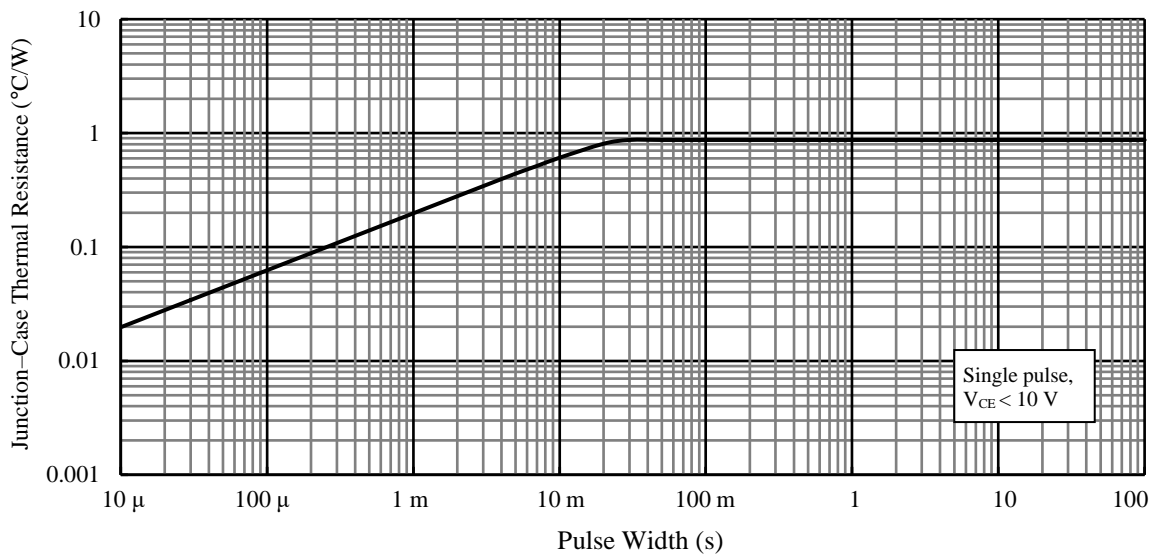
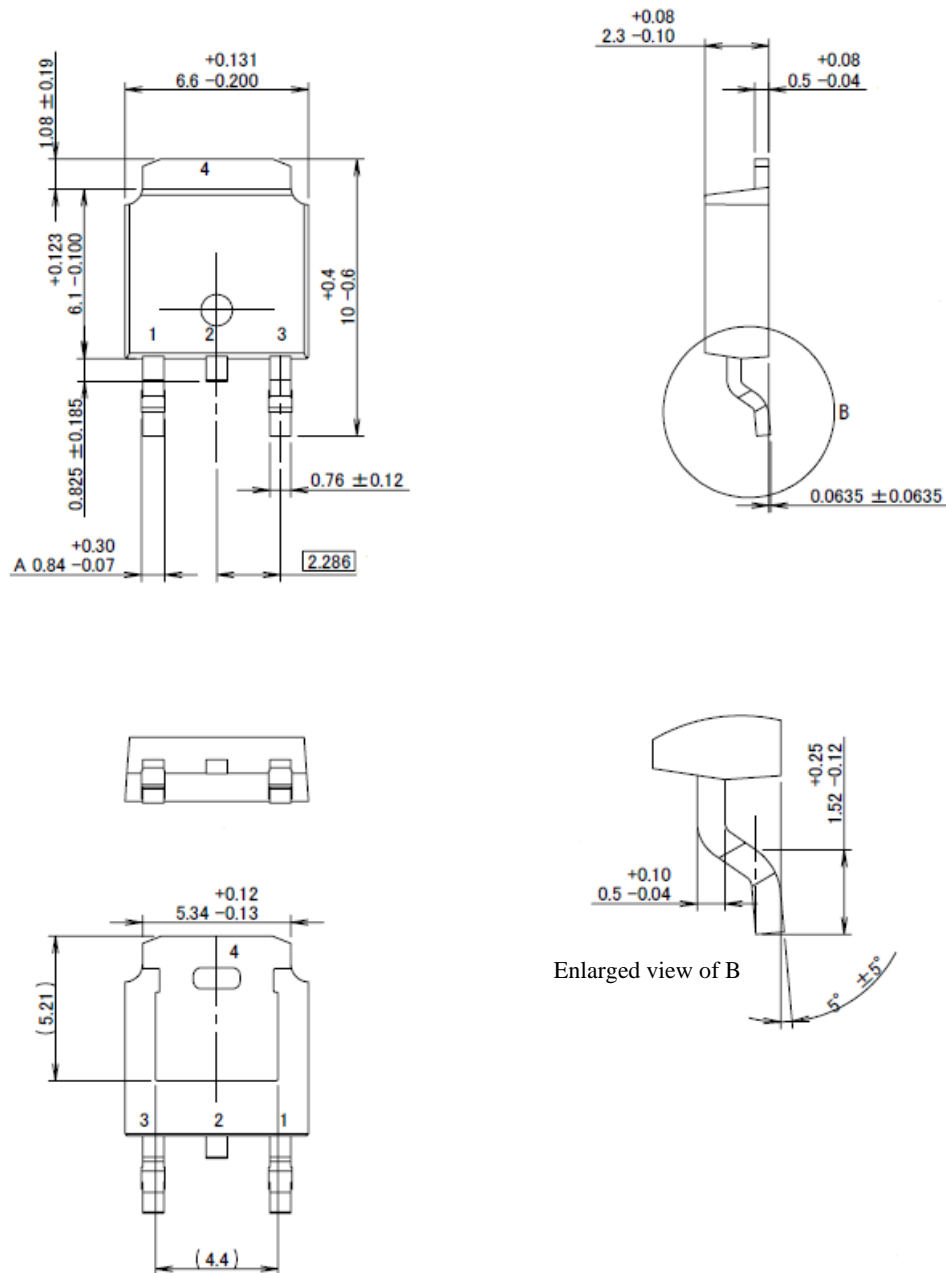


Figure 20. Typical Transient Thermal Resistance Characteristics

# DGU4020GR

## Physical Dimensions

### ● TO252-2L Package

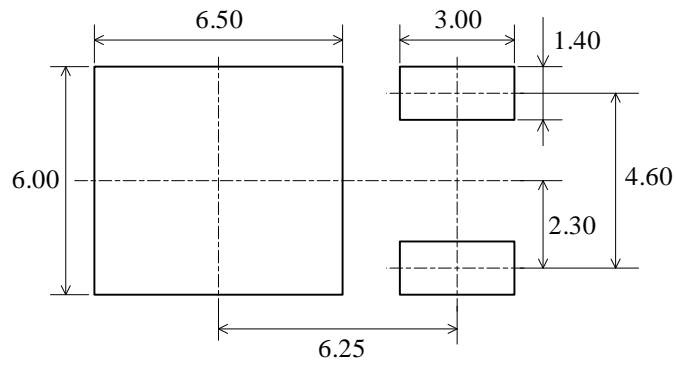


### NOTES:

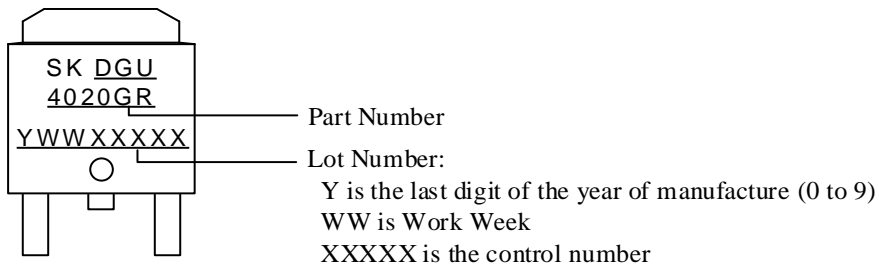
- Dimensions in millimeters
- All the dimensions exclude mold flashes, protrusions, and gate burrs.
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits:
  - Reflow
    - Preheat:  $150\text{ }^\circ\text{C}$  to  $200\text{ }^\circ\text{C}$  / 60 s to 120 s
    - Solder heating:  $255\text{ }^\circ\text{C}$  / 30 s, 3 times ( $260\text{ }^\circ\text{C}$  peak)
    - Soldering iron:  $350\text{ }^\circ\text{C}$  / 3.5 s, 1 time

# DGU4020GR

## • TO252-2L Land Pattern Example



## Marking Diagram



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